

Electroplating of a Printed Circuit Board

Introduction

The printed circuit board (PCB) is the heart of almost any electronic product, carrying the components and copper wires supporting its functionality. This tutorial demonstrates how to simulate copper deposition on a PCB.

This model is also embedded in the *Printed Circuit Board Electroplating Designer* app, which adds a tailor-made user interface. In the app, functionality from the Optimization Module is also used to optimize various process parameters in order to, for instance, maximize the deposition rate for a given current distribution uniformity target. In the documentation for the app you can also read more about the PCB fabrication process in general.

The PCB pattern in the example is defined by imported ECAD files. The example requires an ECAD Module license.

Model Definition

The model uses the Secondary Current Distribution interface to simulate the current distribution in the deposition cell. Butler-Volmer kinetics is used on both electrode surfaces.

A Total Current boundary condition is used at the anode whereas the cathode is grounded (set to zero electronic potential).

The model geometry is shown in Figure 1. The anodes are a set of stretched blocks at the top of the geometry. The cathode is the PCB pattern located at the center bottom of the cell. An isolating screen with an aperture is placed between the anodes and the cathode to control the current distribution on the PCB. The deposition pattern also contains certain "dummy" parts (current thieves), not used in the final PCB product, that are used in order to make the deposition rate on the PCB more uniform.

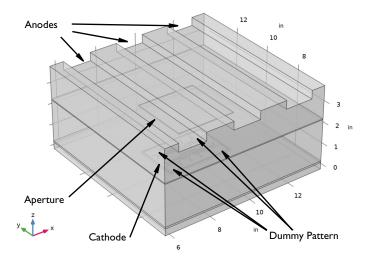


Figure 1: The model geometry.

The conductivity of the metal of the anodes and cathode is very high compared to that of the electrolyte and it is assumed that the electric potential in the metal is constant. The variations in the activation overpotential are therefore caused by the potential in the electrolyte at the surface of the electrodes. Under these assumptions, the electrodes are treated as boundaries in the simulations.

The Secondary Current Distribution interface solves for the electrolyte potential, ϕ_l (V), according to:

$$\mathbf{i}_l = -\sigma_l \nabla \phi_l$$
$$\nabla \cdot \mathbf{i}_l = 0$$

where \mathbf{i}_l (A/m²) is the electrolyte current density vector and σ_l (S/m) is the electrolyte conductivity, which is assumed to be a constant.

The default Insulation condition is used for all boundaries except the anode and cathode surfaces:

$$\mathbf{n} \cdot \mathbf{i}_I = 0$$

where \mathbf{n} is the normal vector, pointing out of the domain.

The main electrode reaction on both the anode and the cathode surfaces is the copper deposition/dissolution reaction,

$$Cu^{2+} + 2e^{-} \Leftrightarrow Cu(s)$$
.

A Butler-Volmer Expression is used to model this reaction; this sets the local current density to

$$i_{\text{loc}} = i_0 \left(\exp \left(\frac{\alpha_a F \eta}{RT} \right) - \exp \left(-\frac{\alpha_c F \eta}{RT} \right) \right)$$

Note that the local current density is positive at the anode surface and negative at the cathode surfaces, depending on the sign of the overpotential, η (V), defined as

$$\eta = \phi_s - \phi_l - E_{eq} \tag{1}$$

where E_{eq} (V) is the equilibrium potential of the copper dissolution/deposition reaction and ϕ_s (V) is the potential of the electronic phase of the electrode.

On both the anode and the cathode the electrolyte current density is set to the local current density of the copper deposition reaction:

$$\mathbf{n} \cdot \mathbf{i}_l = i_{\text{loc}} \tag{2}$$

The anode is grounded in the model whereas the cathode electric potential is solved for by an additional equation in order to fulfill a total current condition on the boundary according to

$$\int i_{loc} = I_{total} = I_{avg} A_{cathode}$$
 (3)

The model is solved in a stationary study.

When postprocessing the solution the deposition thickness, s (m), at the PCB is calculated according to

$$s = \frac{i_{\text{loc}}}{I_{\text{avg}}} s_{\text{target}} \tag{4}$$

where s_{target} (m) is the target mean deposition thickness for the whole cathode.

The time needed to achieve this thickness, $t_{dep}(m)$, is related to s_{target} according to

$$t_{\text{dep}} = s_{\text{target}} \frac{nF}{I_{\text{avg}}} \frac{\rho}{M}$$
 (5)

where M is the mean molar mass (63.55 g/mol) and ρ is the density (8960 kg/m³) of the copper atoms and n (=2) is the number of participating electrons.

Results and Discussion

Figure 2 shows the current density on the cathode, excluding the dummy pattern, for an average current density of 2 A/dm², and Figure 3 shows the corresponding deposited thickness for a target deposition thickness of $10~\mu m$.

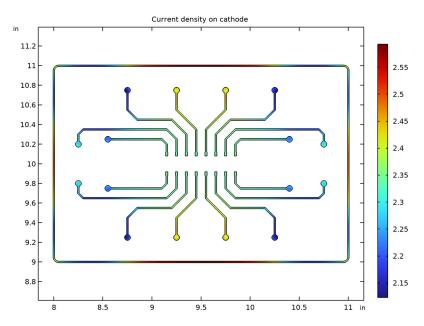


Figure 2: Current density at PCB pattern, excluding the dummy pattern (current thief).

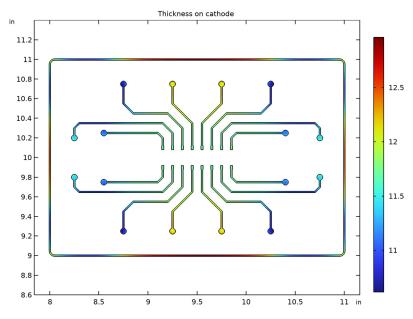


Figure 3: Deposition thickness of the PCB pattern for a target thickness of 10 µm.

Figure 4 shows the effect of the aperture on the field lines, and the thickness for the whole cathode including the dummy pattern. The deposition thickness is lower than $10\ \mu m$ for the dummy parts of the PCB.

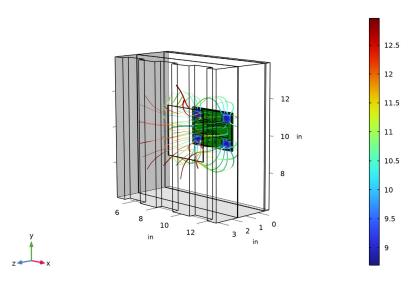


Figure 4: Field lines and thickness on the cathode, including the dummy pattern.

Application Library path: Electrodeposition_Module/Tutorials/pcb_designer

Modeling Instructions

From the File menu, choose New.

NFW

In the New window, click Model Wizard.

MODEL WIZARD

- I In the Model Wizard window, click 1 3D.
- 2 In the Select Physics tree, select Electrochemistry>
 Primary and Secondary Current Distribution>Secondary Current Distribution (cd).
- 3 Click Add.
- 4 Click Study.

- 5 In the Select Study tree, select General Studies>Stationary.
- 6 Click M Done.

GLOBAL DEFINITIONS

Load parameters from a file.

Parameters 1

- I In the Model Builder window, under Global Definitions click Parameters I.
- 2 In the Settings window for Parameters, locate the Parameters section.
- 3 Click Load from File.
- 4 Browse to the model's Application Libraries folder and double-click the file pcb designer parameters.txt.

GEOMETRY I

This model utilizes a premade geometry file containing a PCB pattern imported from an ECAD file. The model geometry is available as a parameterized geometry sequence in a separate MPH-file. If you want to build it from scratch, follow the instructions in the section Appendix — Geometry Modeling Instructions. Otherwise load it from file with the following steps.

- I In the Geometry toolbar, click Insert Sequence and choose Insert Sequence.
- 2 Browse to the model's Application Libraries folder and double-click the file pcb designer geom sequence.mph.
- 3 In the Geometry toolbar, click **Build All**. Use the transparency button to see the entire geometry clearly.
- **4** Click the **Transparency** button in the **Graphics** toolbar. Create some selections that will be used during model setup.

Electrolyte swept mesh region 2

- I In the Geometry toolbar, click \(\frac{1}{2} \) Selections and choose Box Selection.
- 2 In the Settings window for Box Selection, type Electrolyte swept mesh region 2 in the Label text field.
- **3** Locate the **Box Limits** section. In the **z minimum** text field, type 0.
- 4 In the z maximum text field, type 0.

Electrolyte swept mesh regions

I In the Geometry toolbar, click \(\frac{1}{2} \) Selections and choose Union Selection.

- 2 In the Settings window for Union Selection, type Electrolyte swept mesh regions in the Label text field.
- 3 Locate the Input Entities section. Click + Add.
- 4 In the Add dialog box, in the Selections to add list, choose Electrolyte swept mesh region 1 and Electrolyte swept mesh region 2.
- 5 Click OK.

Electrolyte swept mesh regions (unisel2)

- I In the Model Builder window, click Electrolyte swept mesh regions.
- 2 In the Settings window for Union Selection, click **Parallel** Build Selected.

PCB top dielectric

- I In the Geometry toolbar, click \(\frac{1}{2} \) Selections and choose Adjacent Selection.
- 2 In the Settings window for Adjacent Selection, type PCB top dielectric in the Label text field.
- 3 Locate the Input Entities section. Click + Add.
- 4 In the Add dialog box, select Cathode in the Input selections list.
- 5 Click OK.
- 6 In the Settings window for Adjacent Selection, locate the Input Entities section.
- 7 From the Geometric entity level list, choose Boundary.
- 8 Click + Add.
- 9 In the Add dialog box, select Cathode in the Input selections list.
- IO Click OK.

PCB tob dielectric (adjsel1)

- I In the Model Builder window, click PCB top dielectric.
- 2 In the Settings window for Adjacent Selection, click Pauld Selected.

PCB tob

- I In the Geometry toolbar, click \(\frac{1}{2} \) Selections and choose Union Selection.
- 2 In the Settings window for Union Selection, type PCB top in the Label text field.
- **3** Locate the **Geometric Entity Level** section. From the **Level** list, choose **Boundary**.
- **4** Locate the **Input Entities** section. Click + **Add**.
- 5 In the Add dialog box, in the Selections to add list, choose Cathode and PCB top dielectric.
- 6 Click OK.

PCB tob (unisel3)

- I In the Model Builder window, click PCB top.
- 2 In the Settings window for Union Selection, click | Build Selected.

PCB without cathode

- I In the Geometry toolbar, click \(\frac{1}{2} \) Selections and choose Difference Selection.
- 2 In the Settings window for Difference Selection, type PCB without cathode in the Label text field.
- 3 Locate the Input Entities section. Click + Add.
- 4 In the Add dialog box, select PCB in the Selections to add list.
- 5 Click OK.
- 6 In the Settings window for Difference Selection, locate the Input Entities section.
- 7 Click + Add.
- 8 In the Add dialog box, select Cathode in the Selections to subtract list.
- 9 Click OK.
- 10 In the Settings window for Difference Selection, locate the Geometric Entity Level section.
- II From the Level list, choose Boundary.
- 12 Locate the Input Entities section. Click + Add.
- 13 In the Add dialog box, select PCB in the Selections to add list.
- 14 Click OK.
- 15 In the Settings window for Difference Selection, locate the Input Entities section.
- 16 Click + Add.
- 17 In the Add dialog box, select Cathode in the Selections to subtract list.
- 18 Click OK.

DEFINITIONS

Add an integration coupling variable and load variables from a text file.

Integration | (intob|)

- I In the Definitions toolbar, click // Nonlocal Couplings and choose Integration.
- 2 In the Settings window for Integration, locate the Source Selection section.
- 3 From the Geometric entity level list, choose Boundary.
- 4 From the Selection list, choose Cathode.

Variables 1

- I In the Model Builder window, right-click Definitions and choose Variables.
- 2 In the Settings window for Variables, locate the Variables section.
- 3 Click Load from File.
- **4** Browse to the model's Application Libraries folder and double-click the file pcb_designer_variables.txt.

MATERIALS

Add a material to specify the electrolyte conductivity.

Electrolyte

- I In the Model Builder window, under Component I (compl) right-click Materials and choose Blank Material.
- 2 In the Settings window for Material, type Electrolyte in the Label text field.
- **3** Locate the **Material Contents** section. In the table, enter the following settings:

Property	Variable	Value	Unit	Property group
Electrolyte conductivity	sigmal_iso; sigmalii = sigmal_iso, sigmalij = 0	50	S/m	Electrolyte conductivity

SECONDARY CURRENT DISTRIBUTION (CD)

Define the physics settings in the Secondary Current Distribution interface.

Electrode Surface I

- I In the Model Builder window, under Component I (compl) right-click Secondary Current Distribution (cd) and choose Electrode Surface.
- 2 In the Settings window for Electrode Surface, locate the Boundary Selection section.
- 3 From the Selection list, choose Cathode.
- 4 Locate the Electrode Phase Potential Condition section. From the Electrode phase potential condition list, choose Total current.
- **5** In the $I_{1,\text{total}}$ text field, type -ItotCathode.

Electrode Reaction 1

- I In the Model Builder window, click Electrode Reaction I.
- 2 In the Settings window for Electrode Reaction, locate the Electrode Kinetics section.
- **3** From the Kinetics expression type list, choose Butler-Volmer.

- **4** In the i_0 text field, type i0.
- **5** In the α_a text field, type alphaa.

Electrode Surface 2

- I In the Physics toolbar, click **Boundaries** and choose **Electrode Surface**.
- 2 In the Settings window for Electrode Surface, locate the Boundary Selection section.
- **3** From the **Selection** list, choose **Anode**.

Electrode Reaction 1

- I In the Model Builder window, click Electrode Reaction I.
- 2 In the Settings window for Electrode Reaction, locate the Electrode Kinetics section.
- 3 From the Kinetics expression type list, choose Butler-Volmer.
- **4** In the i_0 text field, type i0.
- **5** In the α_a text field, type alphaa.

Initial Values 1

- I In the Model Builder window, under Component I (compl)> Secondary Current Distribution (cd) click Initial Values I.
- 2 In the Settings window for Initial Values, locate the Initial Values section.
- **3** In the *phil* text field, type phil initial.

MESH I

Generate the mesh as follows.

Free Triangular I

In the Mesh toolbar, click A Boundary and choose Free Triangular.

Size

- I In the Model Builder window, click Size.
- 2 In the Settings window for Size, locate the Element Size section.
- 3 From the Predefined list, choose Fine.

Free Triangular 1

- I In the Model Builder window, click Free Triangular I.
- 2 In the Settings window for Free Triangular, locate the Boundary Selection section.
- 3 From the Selection list, choose PCB top.

Size 1

I Right-click Free Triangular I and choose Size.

- 2 In the Settings window for Size, locate the Geometric Entity Selection section.
- 3 From the Selection list, choose Cathode.
- 4 Locate the Element Size section. From the Predefined list, choose Extra fine.

Swebt I

- I In the Mesh toolbar, click A Swept.
- 2 In the Settings window for Swept, locate the Domain Selection section.
- 3 From the Geometric entity level list, choose Domain.
- 4 From the Selection list, choose Electrolyte swept mesh regions.
- 5 Click to expand the Source Faces section. Click Paste Selection.
- 6 In the Paste Selection dialog box, type 9 in the Selection text field.
- 7 Click OK.
- 8 In the Settings window for Swept, click to expand the Sweep Method section.
- 9 From the Face meshing method list, choose Triangular (generate prisms).

Size 1

- I Right-click Swept I and choose Size.
- 2 In the Settings window for Size, locate the Geometric Entity Selection section.
- 3 From the Geometric entity level list, choose Boundary.
- 4 Click Paste Selection.
- 5 In the Paste Selection dialog box, type 9 in the Selection text field.
- 6 Click OK.
- 7 In the Settings window for Size, locate the Element Size section.
- 8 From the Predefined list, choose Finer.

Distribution I

- I In the Model Builder window, right-click Swept I and choose Distribution.
- 2 In the Settings window for Distribution, locate the Distribution section.
- 3 In the **Number of elements** text field, type round((PCBThickness/1.5[mm]>=1)* PCBThickness/1.5[mm]+(PCBThickness/1.5[mm]<1),0).

Distribution 2

- I Right-click Swept I and choose Distribution.
- 2 In the Settings window for Distribution, locate the Domain Selection section.
- 3 From the Selection list, choose Electrolyte swept mesh region 2.

4 Locate the Distribution section. In the Number of elements text field, type ((PCBOffset-PCBThickness)/2[mm]>=1)*(PCBOffset-PCBThickness)/2[mm]+ ((PCBOffset-PCBThickness)/2[mm]<1).

Swebt 2

- I In the Mesh toolbar, click A Swept.
- 2 In the Settings window for Swept, locate the Domain Selection section.
- 3 From the Geometric entity level list, choose Domain.
- **4** From the **Selection** list, choose **Aperture**.
- 5 Locate the Source Faces section. From the Selection list, choose Aperture source.
- 6 Locate the Sweep Method section. From the Face meshing method list, choose Triangular (generate prisms).

Size 1

- I Right-click Swept 2 and choose Size.
- 2 In the Settings window for Size, locate the Geometric Entity Selection section.
- **3** From the **Geometric entity level** list, choose **Boundary**.
- 4 From the Selection list, choose Aperture source.
- 5 Locate the Element Size section. From the Predefined list, choose Finer.

Distribution I

- I In the Model Builder window, right-click Swept 2 and choose Distribution.
- 2 In the Settings window for Distribution, locate the Distribution section.
- 3 In the Number of elements text field, type (ApertureThickness/1.5[mm]>=1)* ApertureThickness/1.5[mm]+(ApertureThickness/1.5[mm]<1).

Free Tetrahedral I

- I In the Mesh toolbar, click A Free Tetrahedral.
- 2 In the Model Builder window, right-click Mesh I and choose Build All.

STUDY I

Finally, compute the results.

Solution I (soll)

- I In the Study toolbar, click Show Default Solver.
- 2 In the Model Builder window, expand the Solution I (soll) node, then click Stationary Solver 1.

- 3 In the Settings window for Stationary Solver, locate the General section.
- 4 In the Relative tolerance text field, type 1e-6.
- 5 In the Model Builder window, click Study 1.
- 6 In the Settings window for Study, locate the Study Settings section.
- 7 Clear the Generate default plots check box.
- 8 In the Study toolbar, click **Compute**.

RESULTS

Create some datasets that will be used during postprocessing.

I In the Model Builder window, expand the Results node.

Cathode

- I In the Model Builder window, expand the Results>Datasets node.
- 2 Right-click Results>Datasets and choose Surface.
- 3 In the Settings window for Surface, type Cathode in the Label text field.
- 4 Locate the Parameterization section. From the x- and y-axes list, choose Expression.
- **5** Locate the **Selection** section. From the **Selection** list, choose **Cathode**.

Cathode copper layout

- I In the Results toolbar, click More Datasets and choose Surface.
- 2 In the Settings window for Surface, type Cathode copper layout in the Label text field.
- 3 Locate the Parameterization section. From the x- and y-axes list, choose Expression.
- 4 Locate the Selection section. From the Selection list, choose PCB copper layout.

PCB without cathode

- I In the Results toolbar, click More Datasets and choose Surface.
- 2 In the Settings window for Surface, type PCB without cathode in the Label text field.
- 3 Locate the Selection section. From the Selection list, choose PCB without cathode.

Walls

- I In the Results toolbar, click More Datasets and choose Surface.
- 2 In the Settings window for Surface, type Walls in the Label text field.
- 3 Locate the Selection section. Click Paste Selection.
- 4 In the Paste Selection dialog box, type 1-5, 7-8, 11-12 in the Selection text field.
- 5 Click OK.

Thickness on cathode

First, plot the thickness on the cathode copper layout.

- I In the Results toolbar, click **2D Plot Group**.
- 2 In the Settings window for 2D Plot Group, type Thickness on cathode in the Label text field.
- 3 Locate the Data section. From the Dataset list, choose Cathode copper layout.

Surface I

- I Right-click Thickness on cathode and choose Surface.
- 2 In the Settings window for Surface, click Replace Expression in the upper-right corner of the Expression section. From the menu, choose Component I (compl)>Definitions> Variables>thickness cathode - Thickness on cathode - m.
- 3 Locate the Expression section. From the Unit list, choose µm.

Thickness on cathode

- I In the Model Builder window, click Thickness on cathode.
- 2 In the Settings window for 2D Plot Group, click to expand the Title section.
- 3 From the Title type list, choose Label.

Current density on cathode

Next, plot the current density on the cathode copper layout.

- I Right-click Thickness on cathode and choose Duplicate.
- 2 In the Settings window for 2D Plot Group, type Current density on cathode in the Label text field.

Surface I

- I In the Model Builder window, expand the Thickness on cathode I node, then click Results>Current density on cathode>Surface 1.
- 2 In the Settings window for Surface, click Replace Expression in the upper-right corner of the Expression section. From the menu, choose Component I (compl)> Secondary Current Distribution>Electrode kinetics>cd.iloc_erI - Local current density - A/ m².
- 3 Locate the Expression section. In the Expression text field, type -cd.iloc er1.
- 4 In the **Unit** field, type A/dm^2.
- **5** Select the **Description** check box.
- 6 In the associated text field, type Current Density on Cathode.

Current density on cathode

- I In the Model Builder window, click Current density on cathode.
- 2 In the Current density on cathode toolbar, click **Plot**.

Thickness distribution and Electric field lines

Next, plot the thickness distribution and the electric field lines.

- I In the Home toolbar, click **Add Plot Group** and choose **3D Plot Group**.
- 2 In the **Settings** window for **3D Plot Group**, type Thickness distribution and Electric field lines in the **Label** text field.

Surface I

- I Right-click Thickness distribution and Electric field lines and choose Surface.
- 2 In the Settings window for Surface, locate the Data section.
- 3 From the Dataset list, choose Cathode.
- 4 Locate the Expression section. In the Expression text field, type thickness_cathode.
- **5** From the **Unit** list, choose μm .

Surface 2

- In the Model Builder window, right-click Thickness distribution and Electric field lines and choose Surface.
- 2 In the Settings window for Surface, locate the Data section.
- 3 From the Dataset list, choose PCB without cathode.
- 4 Locate the Coloring and Style section. From the Coloring list, choose Uniform.
- 5 From the Color list, choose Custom.
- **6** On Windows, click the colored bar underneath, or if you are running the cross-platform desktop the **Color** button.
- 7 Click Define custom colors.
- 8 Set the RGB values to 9, 118, and 9, respectively.
- 9 Click Add to custom colors.
- **10** Click **Show color palette only** or **OK** on the cross-platform desktop.

Surface 3

- I Right-click Thickness distribution and Electric field lines and choose Surface.
- 2 In the Settings window for Surface, locate the Data section.
- 3 From the Dataset list, choose Walls.
- **4** Locate the **Expression** section. In the **Expression** text field, type 1.

- 5 Locate the Coloring and Style section. From the Coloring list, choose Uniform.
- 6 From the Color list, choose White.

Streamline 1

- I Right-click Thickness distribution and Electric field lines and choose Streamline.
- 2 In the Settings window for Streamline, locate the Streamline Positioning section.
- 3 In the Number text field, type 50.
- 4 Locate the Selection section. From the Selection list, choose Cathode.
- 5 Locate the Coloring and Style section. Find the Line style subsection. From the Type list, choose Ribbon.

Color Expression 1

- I Right-click Streamline I and choose Color Expression.
- 2 In the Settings window for Color Expression, locate the Coloring and Style section.
- 3 Clear the Color legend check box.

Thickness distribution and Electric field lines

- I In the Model Builder window, under Results click Thickness distribution and Electric field lines.
- 2 In the Settings window for 3D Plot Group, click to expand the Title section.
- 3 From the Title type list, choose Label.
- 4 In the Thickness distribution and Electric field lines toolbar, click **Plot**.

Appendix — Geometry Modeling Instructions

From the File menu, choose New.

In the New window, click Model Wizard.

MODEL WIZARD

- I In the Model Wizard window, click **3D**.
- 2 Click M Done.

GLOBAL DEFINITIONS

Parameters 1

- I In the Model Builder window, under Global Definitions click Parameters I.
- 2 In the Settings window for Parameters, locate the Parameters section.
- 3 Click **Load from File**.
- **4** Browse to the model's Application Libraries folder and double-click the file pcb_designer_geom_sequence_parameters.txt.

GEOMETRY I

- I In the Model Builder window, under Component I (compl) click Geometry I.
- 2 In the Settings window for Geometry, locate the Units section.
- 3 From the Length unit list, choose in.

PCB

- I In the Geometry toolbar, click Block.
- 2 In the Settings window for Block, type PCB in the Label text field.
- 3 Locate the Size and Shape section. In the Width text field, type PCBWidth+2* PCBMargin.
- 4 In the **Depth** text field, type PCBHeight+2*PCBMargin.
- 5 In the **Height** text field, type PCBThickness.
- **6** Locate the **Position** section. In the **x** text field, type PCBxMin-PCBMargin.
- 7 In the y text field, type PCByMin-PCBMargin.
- 8 In the z text field, type PCBOffset-PCBThickness.
- **9** Locate the **Selections of Resulting Entities** section. Select the **Resulting objects selection** check box.
- **10** Click the **Transparency** button in the **Graphics** toolbar.

Work Plane I (wbl)

- I In the Geometry toolbar, click Work Plane.
- 2 In the Settings window for Work Plane, locate the Plane Definition section.
- 3 In the z-coordinate text field, type PCBOffset.
- 4 Locate the Selections of Resulting Entities section. Find the Cumulative selection subsection. Click New.
- 5 In the New Cumulative Selection dialog box, type PCB copper layout in the Name text field.

- 6 Click OK.
- 7 In the Settings window for Work Plane, click Show Work Plane.

Work Plane I (wbl)>Import I (imbl)

- I In the **Home** toolbar, click **Import**.
- 2 In the Settings window for Import, locate the Import section.
- 3 Click Browse.
- **4** Browse to the model's Application Libraries folder and double-click the file example pcb.tgz.
- 5 Click Import.
- **6** Find the **Layers to import** subsection. In the table, clear the **Import** check box for Dielectric.

GEOMETRY I

Work Plane I (wpl)

In the Model Builder window, collapse the Component I (compl)>Geometry I> Work Plane I (wpl) node.

If I (if I)

- I In the Model Builder window, right-click Geometry I and choose Programming>If +
- 2 In the Settings window for If, locate the If section.
- 3 In the Condition text field, type UseDummy.

Work Plane 2 (wb2)

- I In the Geometry toolbar, click Work Plane.
- 2 In the Settings window for Work Plane, locate the Plane Definition section.
- 3 In the z-coordinate text field, type PCBOffset.
- 4 Locate the Selections of Resulting Entities section. Find the Cumulative selection subsection. Click New.
- 5 In the New Cumulative Selection dialog box, type PCB dummy layout in the Name text field.
- 6 Click OK.
- 7 In the Settings window for Work Plane, click Show Work Plane.

Work Plane 2 (wp2)>Import 1 (imp1)

- I In the **Home** toolbar, click **Import**.
- 2 In the Settings window for Import, locate the Import section.
- 3 Click **Browse**.
- **4** Browse to the model's Application Libraries folder and double-click the file example_pcb_dummy_pattern.tgz.
- 5 Click Import.
- 6 Find the Layers to import subsection. In the table, clear the Import check box for Dielectric.

End If I (endif1)

- I In the Model Builder window, under Component I (compl)>Geometry I click End If I (endifl).
- 2 In the Settings window for End If, click Build All Objects.

Cathode

- I In the Model Builder window, right-click Geometry I and choose Selections> Union Selection.
- 2 In the Settings window for Union Selection, type Cathode in the Label text field.
- 3 Locate the Geometric Entity Level section. From the Level list, choose Object.
- **4** Locate the **Input Entities** section. Click + **Add**.
- 5 In the Add dialog box, in the Selections to add list, choose PCB copper layout and PCB dummy layout.
- 6 Click OK.

Bath

- I In the Geometry toolbar, click | Block.
- 2 In the Settings window for Block, type Bath in the Label text field.
- 3 Locate the Size and Shape section. In the Width text field, type BathWidth.
- 4 In the **Depth** text field, type BathHeight.
- 5 In the **Height** text field, type BathDepth.
- 6 Locate the Position section. In the x text field, type PCBxMin-(BathWidth-PCBWidth)/2.
- 7 In the y text field, type PCByMin-(BathHeight-PCBHeight)/2.
- 8 Locate the Selections of Resulting Entities section. Select the Resulting objects selection check box.

Electrolyte swept mesh region I

- I In the **Geometry** toolbar, click **Block**.
- 2 In the Settings window for Block, type Electrolyte swept mesh region 1 in the Label text field.
- 3 Locate the Size and Shape section. In the Width text field, type BathWidth.
- 4 In the **Depth** text field, type BathHeight.
- 5 In the **Height** text field, type PCBThickness.
- 6 Locate the **Position** section. In the x text field, type PCBxMin-(BathWidth-PCBWidth)/ 2.
- 7 In the y text field, type PCByMin-(BathHeight-PCBHeight)/2.
- 8 In the z text field, type PCBOffset-PCBThickness.
- 9 Locate the Selections of Resulting Entities section. Select the Resulting objects selection check box.

Work Plane 3 (wb3)

- I In the Geometry toolbar, click Work Plane.
- 2 In the Settings window for Work Plane, locate the Plane Definition section.
- 3 From the Plane type list, choose Face parallel.
- **4** Click the **Zoom Extents** button in the **Graphics** toolbar.
- 5 On the object blk2, select Boundary 4 only.
- 6 Click Show Work Plane.

Work Plane 3 (wb3)>Rectangle 1 (r1)

- I In the Work Plane toolbar, click Rectangle.
- 2 In the Settings window for Rectangle, locate the Size and Shape section.
- 3 In the Width text field, type BathWidth/6.
- 4 In the Height text field, type BathHeight.
- 5 Locate the **Position** section. In the **xw** text field, type -BathWidth/2+BathWidth/6/2.
- 6 In the yw text field, type -BathHeight/2.

Work Plane 3 (wp3)>Array I (arr1)

- I In the Work Plane toolbar, click \(\sum_{i} \) Transforms and choose Array.
- 2 Click the Zoom Extents button in the Graphics toolbar.
- **3** Select the object **rI** only.
- 4 In the Settings window for Array, locate the Size section.

- 5 In the xw size text field, type 3.
- 6 Locate the **Displacement** section. In the xw text field, type BathWidth/3.

GEOMETRY I

Work Plane 3 (wp3)

In the Model Builder window, collapse the Component I (compl)>Geometry I> Work Plane 3 (wp3) node.

Anode

- I In the Geometry toolbar, click Extrude.
- 2 In the Settings window for Extrude, type Anode in the Label text field.
- **3** Locate the **Distances** section. In the table, enter the following settings:

Distances (in)

AnodeThickness

- 4 Select the Reverse direction check box.
- 5 Locate the Selections of Resulting Entities section. Select the Resulting objects selection check box.
- 6 From the Show in physics list, choose Boundary selection.

Difference I (dif1)

- I Right-click Geometry I and choose Booleans and Partitions>Difference.
- 2 Select the objects blk2 and blk3 only.
- 3 In the Settings window for Difference, locate the Difference section.
- 4 Find the **Objects to subtract** subsection. Click to select the Activate Selection toggle button.
- 5 From the Objects to subtract list, choose PCB.
- 6 Select the objects blk1 and ext1 only.

If 2 (if2)

- I In the Geometry toolbar, click Programming and choose If + End If.
- 2 In the Settings window for If, locate the If section.
- 3 In the Condition text field, type UseAperture.

Work Plane 4 (wb4)

I In the Geometry toolbar, click Work Plane.

- 2 In the Settings window for Work Plane, locate the Plane Definition section.
- 3 In the z-coordinate text field, type ApertureOffset+PCBOffset.
- 4 Click Show Work Plane.

Work Plane 4 (wp4)>Cross Section 1 (cro1)

- I In the Work Plane toolbar, click Cross Section.
- 2 In the Settings window for Cross Section, locate the Cross Section section.
- **3** From the **Intersect** list, choose **Selected objects**.
- 4 Find the Objects to intersect subsection. Click to select the Activate Selection toggle button.
- **5** From the **Objects to intersect** list, choose **Bath**.

GEOMETRY I

Work Plane 4 (wb4)

- I In the Model Builder window, collapse the Component I (compl)>Geometry I> Work Plane 4 (wp4) node.
- 2 In the Model Builder window, click Work Plane 4 (wp4).
- 3 In the Settings window for Work Plane, click **Build Selected**.

Extrude 2 (ext2)

- I In the Model Builder window, right-click Geometry I and choose Extrude.
- 2 In the Settings window for Extrude, locate the Distances section.
- **3** In the table, enter the following settings:

Distances (in)

ApertureThickness

4 Click | Build Selected.

Difference 2 (dif2)

- I In the Geometry toolbar, click Booleans and Partitions and choose Difference.
- **2** Select the object **difl** only.
- 3 In the Settings window for Difference, locate the Difference section.
- 4 Find the Objects to subtract subsection. Click to select the Activate Selection toggle button.
- **5** Select the object **ext2** only.

6 Click | Build Selected.

Aperture source

- I In the Geometry toolbar, click Work Plane.
- 2 In the Settings window for Work Plane, type Aperture source in the Label text field.
- 3 Locate the Plane Definition section. In the z-coordinate text field, type ApertureOffset+PCBOffset.
- 4 Locate the Selections of Resulting Entities section. Select the Resulting objects selection check box.
- 5 Click Show Work Plane.

Aperture source (wp5)>Rectangle I (rI)

- I In the Work Plane toolbar, click Rectangle.
- 2 In the Settings window for Rectangle, locate the Size and Shape section.
- **3** In the **Width** text field, type ApertureWidth.
- 4 In the **Height** text field, type ApertureHeight.
- 5 Locate the **Position** section. In the xw text field, type PCBxMin-(BathWidth-PCBWidth)/2+(BathWidth-ApertureWidth)/2.
- 6 In the yw text field, type PCByMin-(BathHeight-PCBHeight)/2+(BathHeight-ApertureHeight)/2.

Aperture source (wp5)

- I In the Model Builder window, collapse the Component I (compl)>Geometry I> Aperture source (wp5) node.
- 2 In the Model Builder window, click Aperture source (wp5).
- 3 In the Settings window for Work Plane, click Plane Build Selected.

Aberture

- I In the Geometry toolbar, click **Extrude**.
- 2 In the Settings window for Extrude, type Aperture in the Label text field.
- **3** Locate the **Distances** section. In the table, enter the following settings:

Distances (in) ApertureThickness

4 Locate the Selections of Resulting Entities section. Select the Resulting objects selection check box.

Form Union (fin)

In the Geometry toolbar, click **Build All**.